

IN THE SPECIFICATION

Please amend the paragraph at page 21, line 18, to page 22, line 1 as follows:

The coil 22 has a layered structure in which a plurality of wire layers 28 (~~four~~ three layers, in this embodiment) are piled up in the thickness direction, so that a high aspect ratio is attained. The coil 22 is formed in a spiral shape with a constant radial pitch from the inner portion to the outer portion. This coil 22 can be formed utilizing a thin film process that is used in producing semiconductor devices. In the following, a process of forming the coil 22 by means of a thin film process will be described.